

Reliability Tests for Switches Used in Telecommunication Networks

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Abstract

The results of several reliability tests concerning switches used in telecommunications networks are presented. Tests were combined ones: temperature and humidity, and the experiment was conducted step-by-step, with failures analysis carried out after each test step, so as to simulate actual operating conditions. An analysis of the results was performed, finally making a series of recommendations on changes in manufacturing technology switches in order to increase their level of reliability.

Keywords: Reliability, Reliability tests, Accelerated tests, Failure analysis, Switches, Telecommunication networks

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